



November 2007

FDP2710

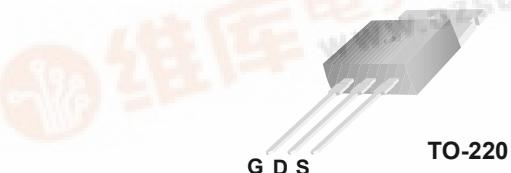
250V N-Channel PowerTrench MOSFET

General Description

This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench process that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

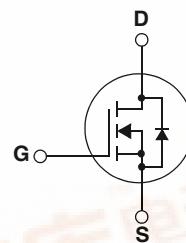
Application

- PDP application



Description

- 50A, 250V, $R_{DS(on)} = 36.3\text{m}\Omega$ @ $V_{GS} = 10\text{ V}$
- Fast switching speed
- Low gate charge
- High performance trench technology for extremely low $R_{DS(on)}$
- High power and current handling capability
- RoHS compliant



Absolute Maximum Ratings

Symbol	Parameter	Ratings	Unit
V_{DS}	Drain-Source Voltage	250	V
V_{GS}	Gate-Source voltage	± 30	V
I_D	Drain Current - Continuous ($T_C = 25^\circ\text{C}$) - Continuous ($T_C = 100^\circ\text{C}$)	50 31.3	A A
I_{DM}	Drain Current - Pulsed	(Note 1)	See Figure 9
E_{AS}	Single Pulsed Avalanche Energy	(Note 2)	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	V/ns
P_D	Power Dissipation ($T_C = 25^\circ\text{C}$) - Derate above 25°C	260 2.1	W W/ $^\circ\text{C}$
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +150	$^\circ\text{C}$
T_L	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds	300	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Min	Max	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	--	0.48	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	--	62.5	$^\circ\text{C/W}$

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDP2710	FDP2710	TO-220	-	-	50

Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}} = 0\text{V}$, $I_D = 250\mu\text{A}$, $T_J = 25^\circ\text{C}$	250	--	--	V
$\frac{\Delta \text{BV}_{\text{DSS}}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = 250\mu\text{A}$, Referenced to 25°C	--	0.25	--	$\text{V}/^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}} = 250\text{V}$, $V_{\text{GS}} = 0\text{V}$ $V_{\text{DS}} = 250\text{V}$, $V_{\text{GS}} = 0\text{V}$, $T_C = 125^\circ\text{C}$	--	--	10 500	μA μA
I_{GSSF}	Gate-Body Leakage Current, Forward	$V_{\text{GS}} = 30\text{V}$, $V_{\text{DS}} = 0\text{V}$	--	--	100	nA
I_{GSSR}	Gate-Body Leakage Current, Reverse	$V_{\text{GS}} = -30\text{V}$, $V_{\text{DS}} = 0\text{V}$	--	--	-100	nA
On Characteristics						
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}} = V_{\text{GS}}$, $I_D = 250\mu\text{A}$	3.0	4.0	5.0	V
$R_{\text{DS}(\text{on})}$	Static Drain-Source On-Resistance	$V_{\text{GS}} = 10\text{V}$, $I_D = 25\text{A}$	--	36.3	42.5	$\text{m}\Omega$
g_{FS}	Forward Transconductance	$V_{\text{DS}} = 10\text{V}$, $I_D = 25\text{A}$	(Note 4)	--	63	--
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{\text{DS}} = 25\text{V}$, $V_{\text{GS}} = 0\text{V}$, $f = 1.0\text{MHz}$	--	5470	7280	pF
C_{oss}	Output Capacitance		--	426	570	pF
C_{rss}	Reverse Transfer Capacitance		--	97	146	pF
Switching Characteristics						
$t_{\text{d}(\text{on})}$	Turn-On Delay Time	$V_{\text{DD}} = 125\text{V}$, $I_D = 50\text{A}$ $V_{\text{GS}} = 10\text{V}$, $R_{\text{GEN}} = 25\Omega$	--	80	170	ns
t_r	Turn-On Rise Time		--	252	515	ns
$t_{\text{d}(\text{off})}$	Turn-Off Delay Time		--	112	235	ns
t_f	Turn-Off Fall Time		--	154	320	ns
Q_g	Total Gate Charge	$V_{\text{DS}} = 125\text{V}$, $I_D = 50\text{A}$ $V_{\text{GS}} = 10\text{V}$	--	78	101	nC
Q_{gs}	Gate-Source Charge		--	34	--	nC
Q_{gd}	Gate-Drain Charge		--	18	--	nC
Drain-Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain-Source Diode Forward Current	$V_{\text{GS}} = 0\text{V}$, $I_S = 50\text{A}$ $V_{\text{DS}} = 50\text{V}$, $I_S = 17\text{A}$ $dI/dt = 100\text{A}/\mu\text{s}$	--	--	50	A
I_{SM}	Maximum Pulsed Drain-Source Diode Forward Current		--	--	150	A
V_{SD}	Drain-Source Diode Forward Voltage		--	--	1.2	V
t_{rr}	Reverse Recovery Time		--	163	--	ns
Q_{rr}	Reverse Recovery Charge		--	1.3	--	μC

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. L = 1mH, $I_{AS} = 17\text{A}$, $V_{DD} = 50\text{V}$, $R_G = 25\Omega$, Starting $T_J = 25^\circ\text{C}$
3. $I_{SD} \leq 50\text{A}$, $di/dt \leq 100\text{A}/\mu\text{s}$, $V_{DD} \leq \text{BV}_{\text{DSS}}$, Starting $T_J = 25^\circ\text{C}$
4. Pulse Test: Pulse width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$
5. Essentially Independent of Operating Temperature Typical Characteristics

Typical Performance Characteristics

Figure 1. On-Region Characteristics

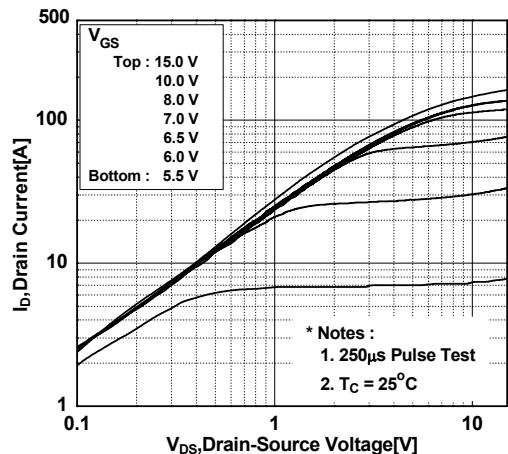


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

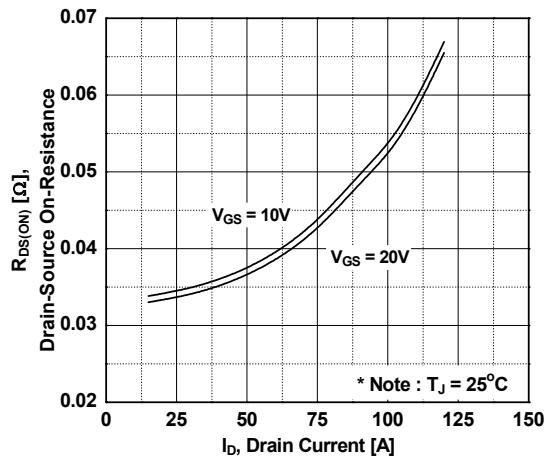


Figure 5. Capacitance Characteristics

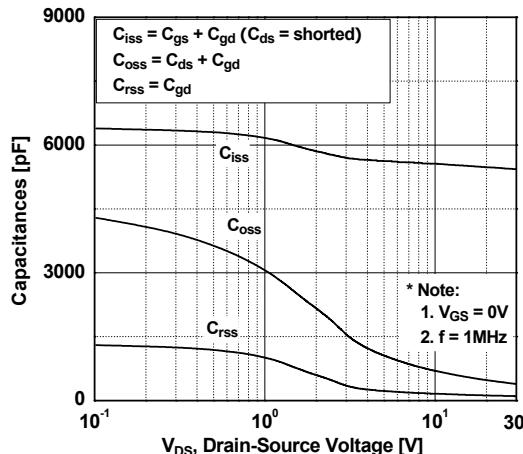


Figure 2. Transfer Characteristics

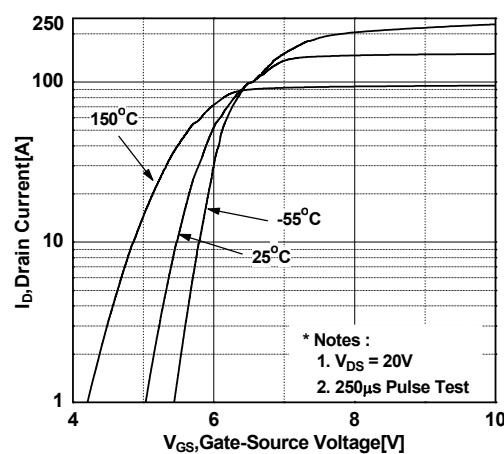


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

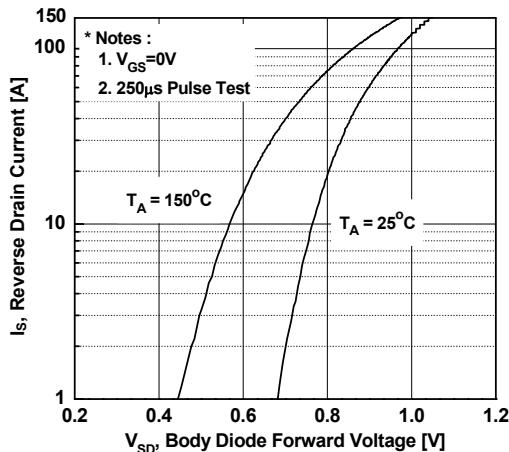
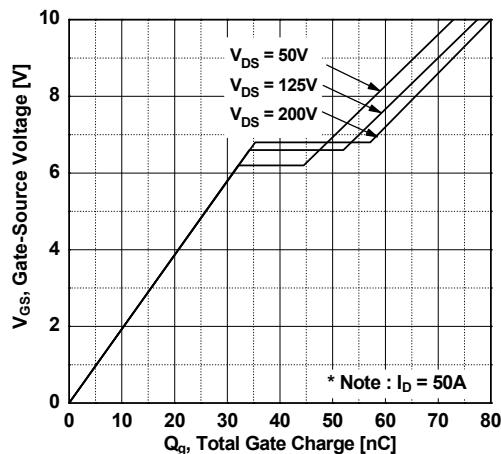


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

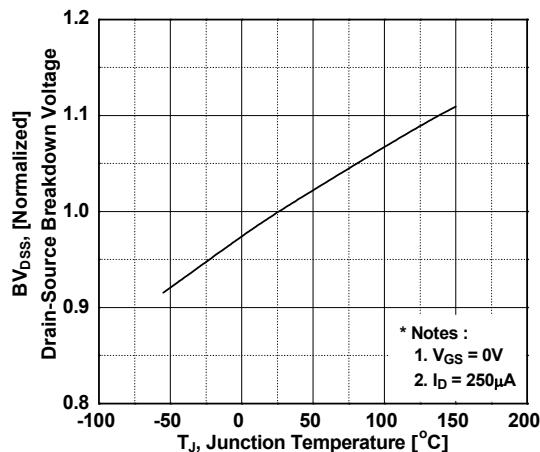


Figure 9. Maximum Safe Operating Area

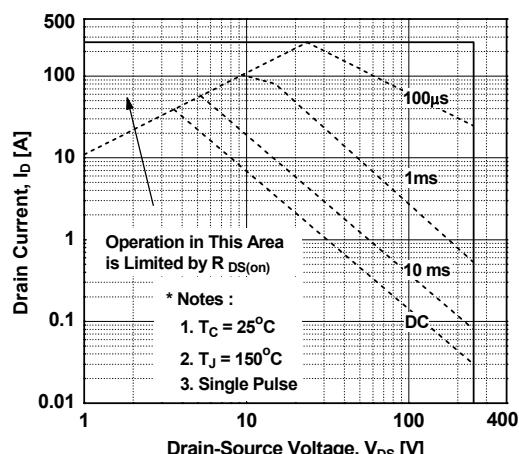


Figure 8. On-Resistance Variation vs. Temperature

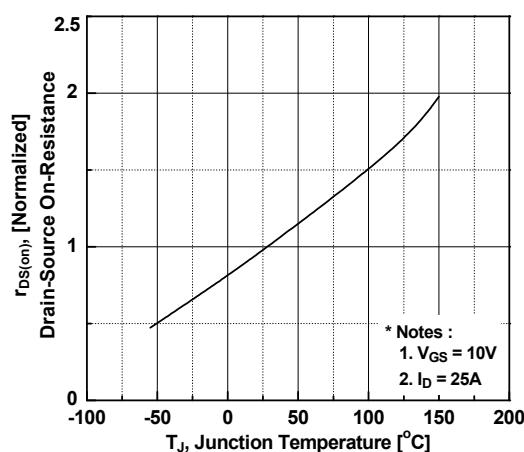


Figure 10. Maximum Drain Current vs. Case Temperature

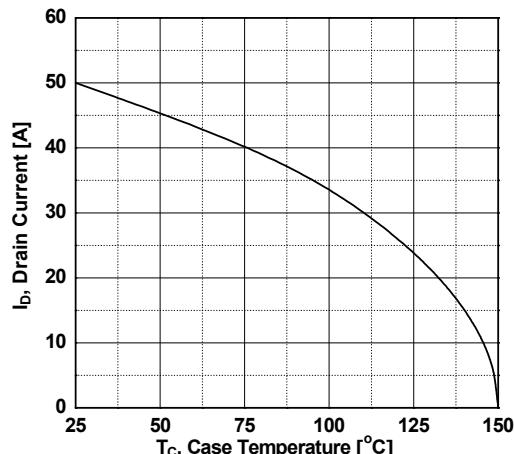
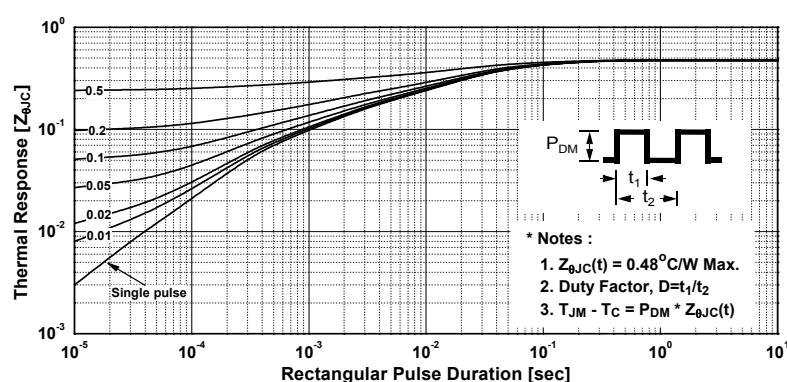
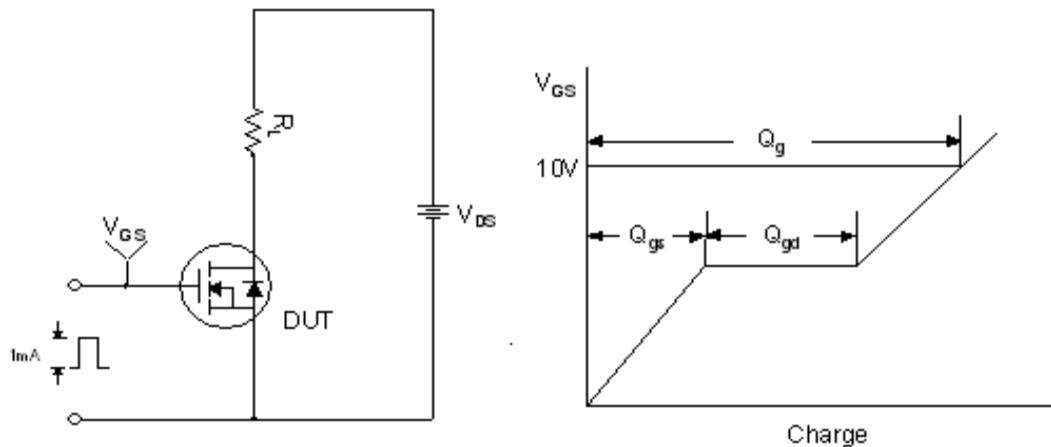


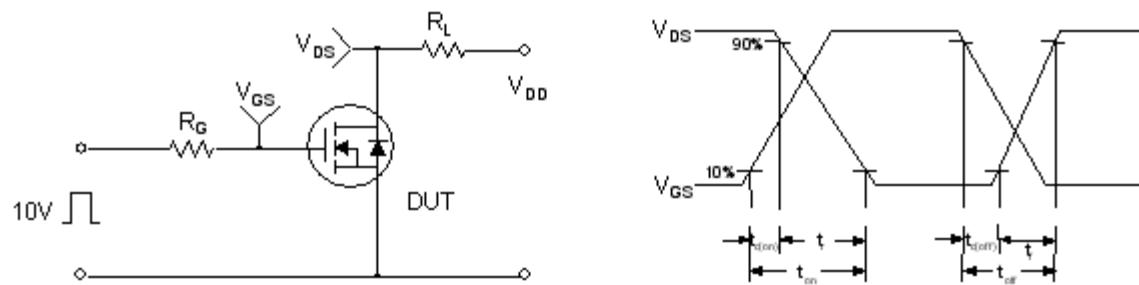
Figure 11. Transient Thermal Response Curve



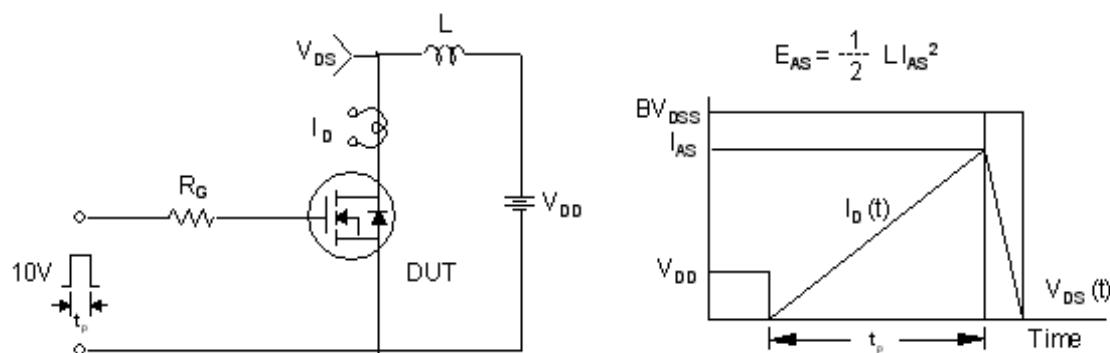
Gate Charge Test Circuit & Waveform



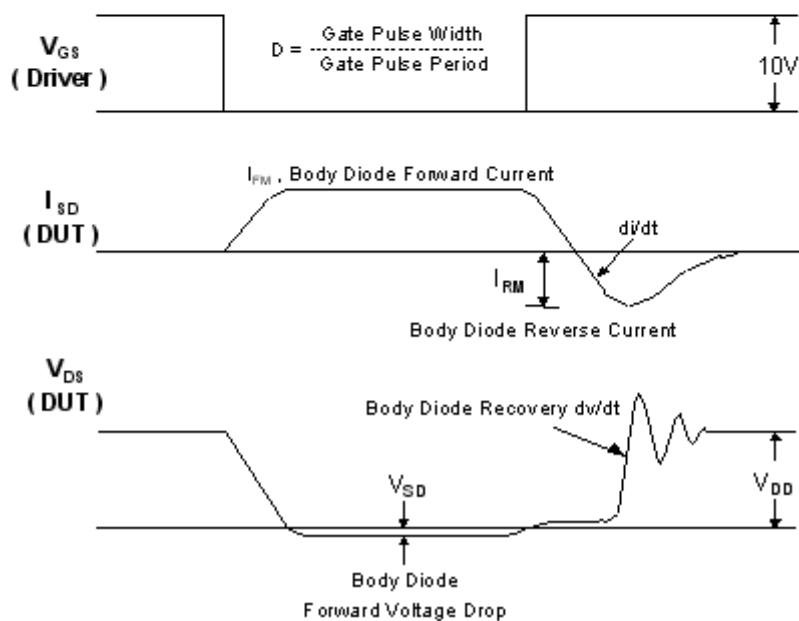
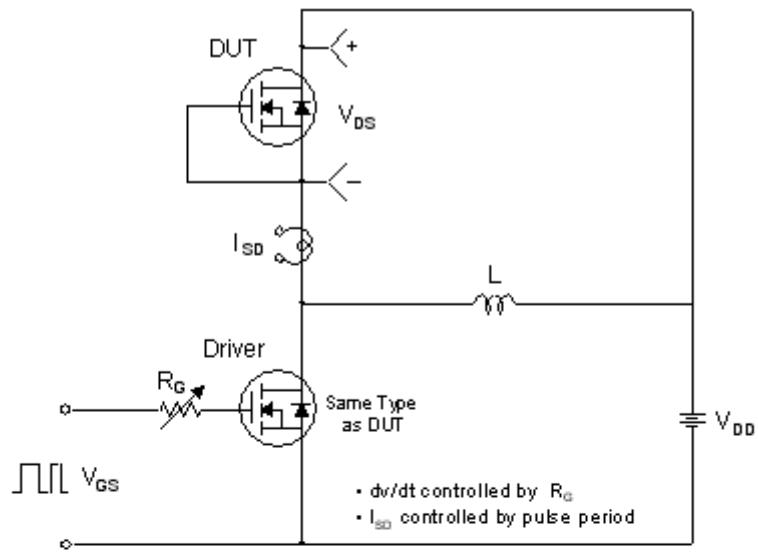
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms

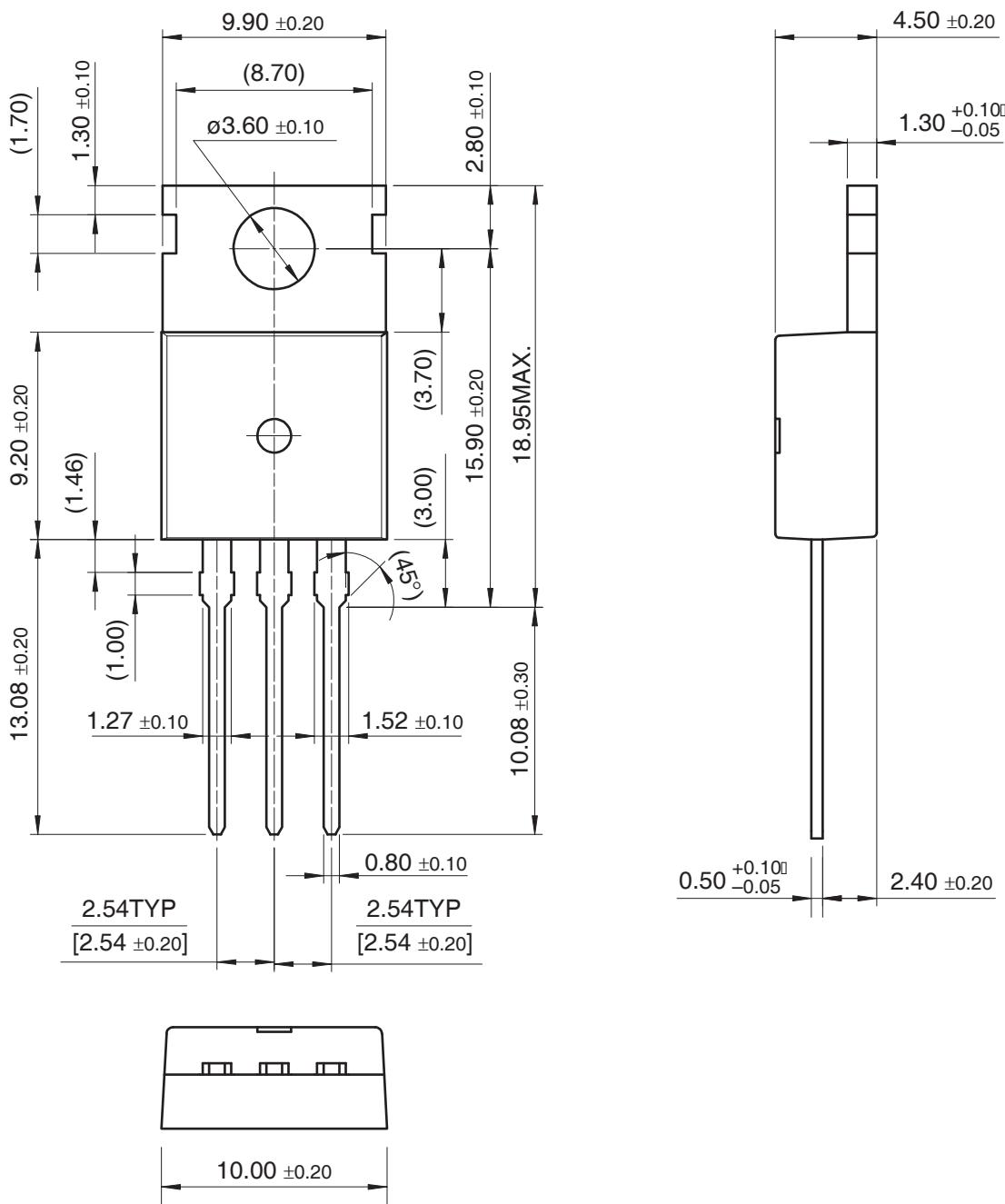


Peak Diode Recovery dv/dt Test Circuit & Waveforms



Mechanical Dimensions

TO-220





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